

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A2			UPDATE SOME DETAILS	11/10'13	Daniel

ORDERING INFORMATION

TFPS- NH5 (XXT)

① ② ③

① **PRODUCT SERIES:**

Micro-SD Connector,
Push-Push type,

② **ITEM NO.**

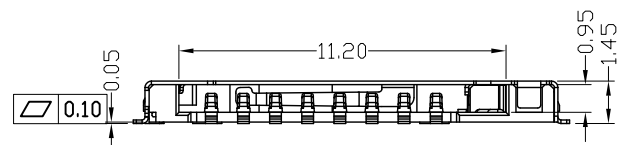
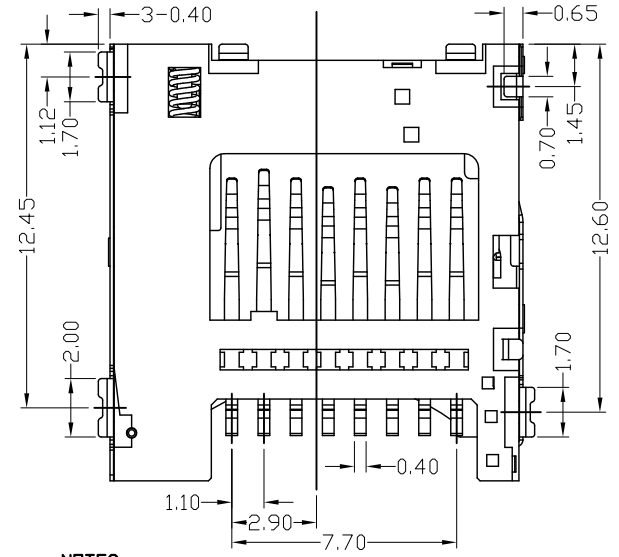
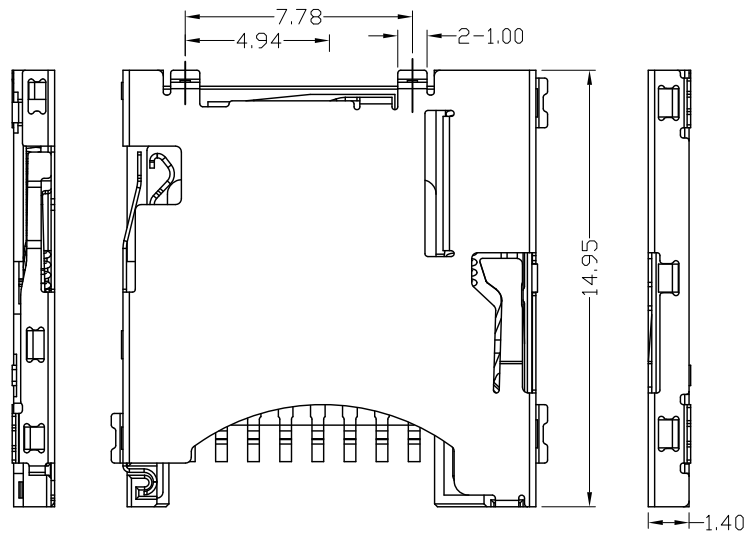
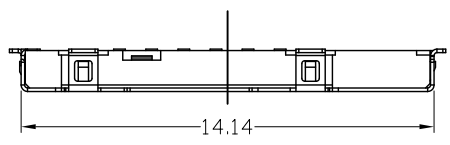
8+2PIN, 1.45mm Height.

CUSTOMER DRAWING

RoHS Compliant

③ **REEL PACKAGE & GOLD PLATING**

01: 1u"
05: 5u"
10: 10u"
15: 15u"
30: 30u"



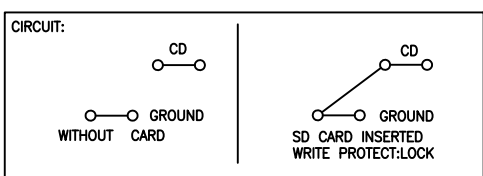
NOTES :

1. MATERIAL :

- 1-1. HOUSING: HIGH TEMP PLASTIC, UL94V-0.
- 1-2. CONTACT: COPPER ALLOY.
- 1-3. SHELL: SUS304.

2. FINISH :

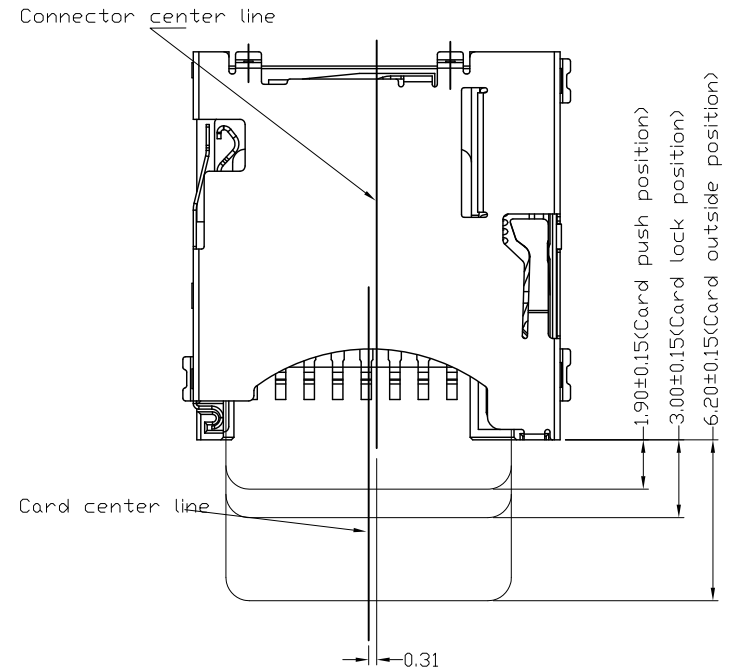
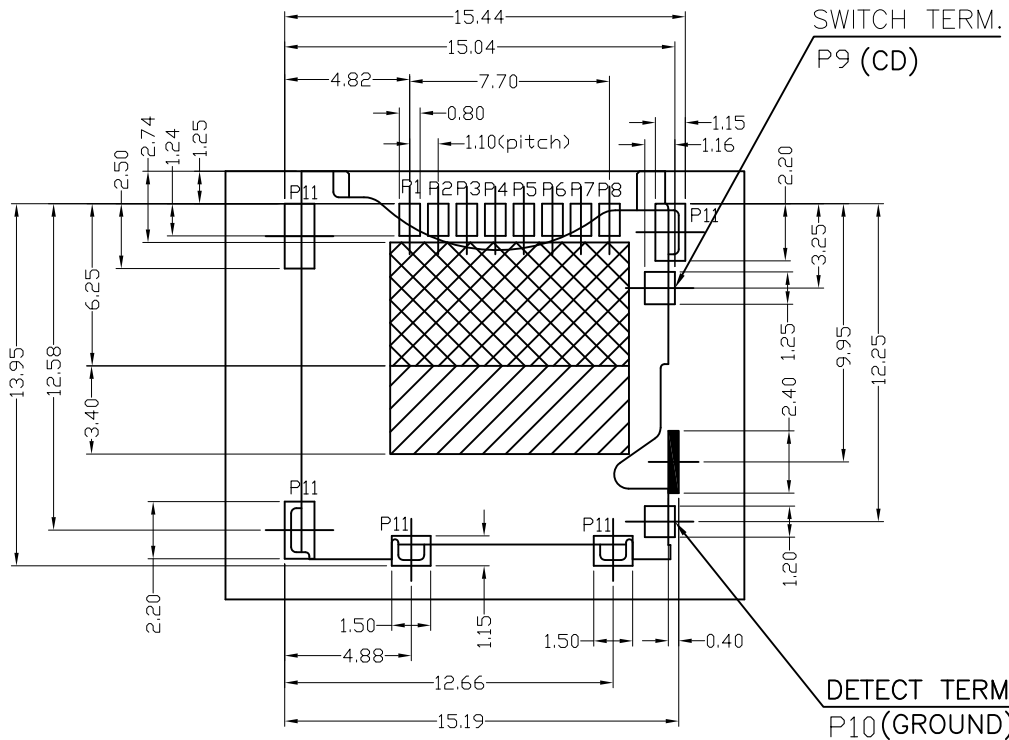
- 2-1. CONTACT: GOLD PLATED OVER NICKEL ON CONTACT AREA.
TIN PLATED OVER NICKEL ON SOLDER TAILS.
- 2-2. SHELL: NICKEL PLATED OVER ALL.



DIM	TOL	DIM	TOL
X.X	±0.30	X.X'	±3.0'
X.XX	±0.20	X.XX'	±2.0'
X.XXX	±0.10	X.XXX'	±1.0'

SUNFUN		SUNFUN TECHNOLOGY LTD			
DRAW NO.	TFPS-NH5(A2)	DATE	MATERIAL: SEE NOTES	DRAW NAME:	
DESIGN:	Daniel	11/10'13	FINISH: SEE NOTES	Micro-SD CONNECTOR:	
CHECK:	Daniel	11/10'13	FILE: TFPS-NH5(A2)	PUSH-PUSH NORMAL TYPE,	
REVIEW:	Jack	11/10'13	P/N: TFPS-NH5(XXT)	8+2PIN/ 1.45H	
APPROVED:	Jack	11/10'13	REV. A2	MODEL: Micro-SD PP CONN	
			SCALE	UNIT: mm	SHEET: 1/2

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- PROHIBITED AREA
- ▨ PATTERN PROHIBITION AREA
- ▩ SOLDER PROHIBITION AREA

PCB PATTERN LAYOUT
(GENERAL TOLERANCE:±0.05)

PIN DEFINE			
P1	DAT2	P7	DAT0
P2	CD/DAT3	P8	DAT1
P3	CMD	P9	MICRO SD-CD
P4	VDD	P10	MICRO SD-GND
P5	CLK	P11	COVER-GND
P6	VSS		

DIM	TOL	DIM	TOL
X.X	±0.30	X.X'	±3.0'
X.XX	±0.20	X.XX'	±2.0'
X.XXX	±0.10	X.XXX'	±1.0'

SUNFUN		SUNFUN TECHNOLOGY LTD			
DRAW NO.	TFPS-NH5(A2)	DATE	MATERIAL: SEE NOTES		DRAW NAME: Micro-SD CONNECTOR: PUSH-PUSH NORMAL TYPE, 8+2PIN/ 1.45H
DESIGN:	Daniel	11/10'13	FINISH: SEE NOTES		
CHECK:	Daniel	11/10'13	FILE: TFPS-NH5(A2)		MODEL: Micro-SD PP CONN
REVIEW:	Jack	11/10'13	P/N: TFPS-NH5(XXT)		UNIT: mm
APPROVED:	Jack	11/10'13	REV. A2	SCALE	SHEET: 2/2